



SOT1181-2

HTQFP48: plastic thermal enhanced thin quad flat package;
48 leads; body 10 mm x 10 mm x 1 mm; exposed die pad

25 July 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFP48
Package type industry code	HTQFP48
Package style descriptive code	HTQFP (thermal enhanced thin quad flat package)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	23-10-2012
Manufacturer package code	SOT1181

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	-	-	-	1.2	mm
A ₂	package height	0.95	-	1	1.05	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	48	-	

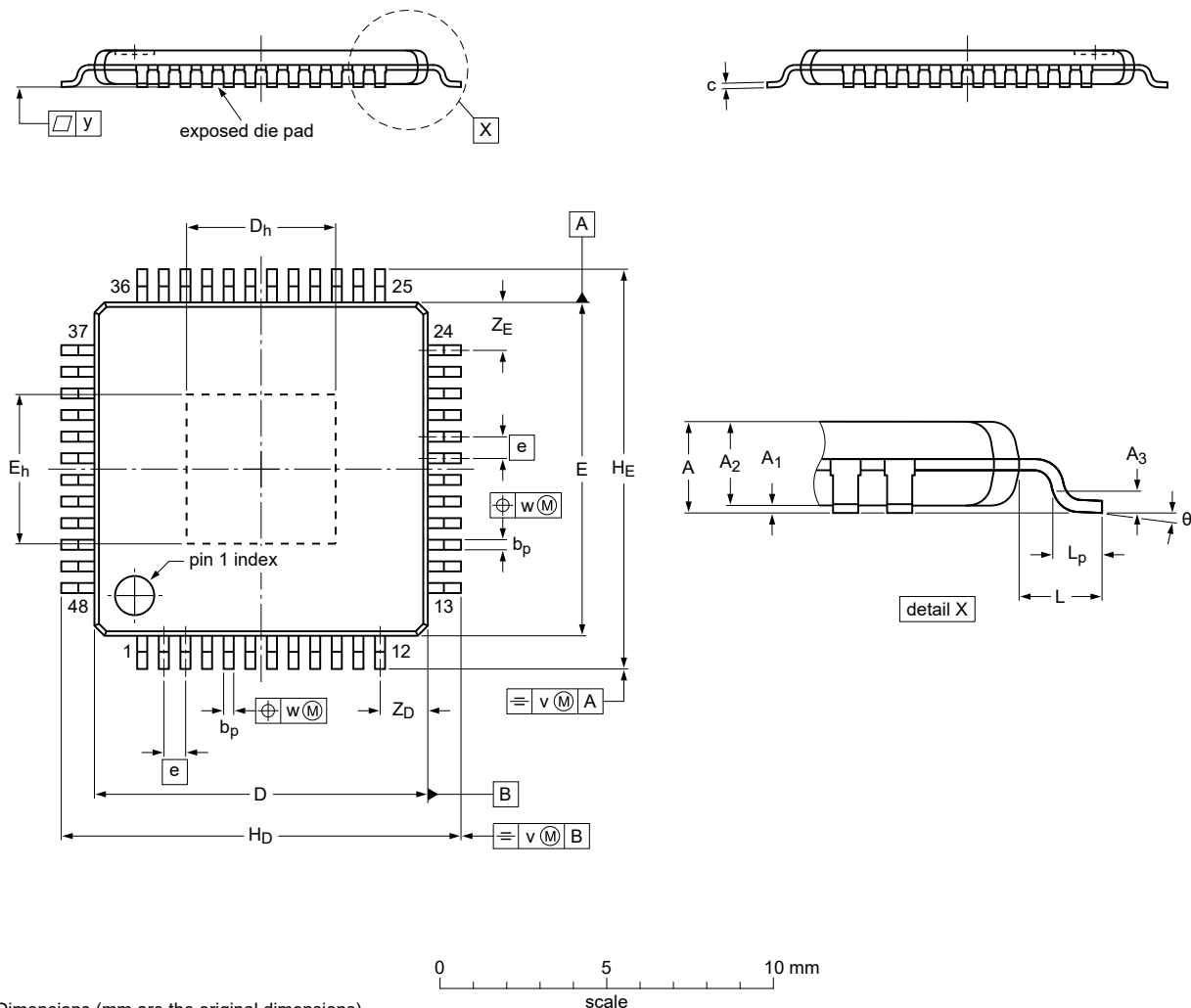


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2. Package outline

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Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
max	1.2	0.125	1.05		0.35	0.18	10.1	5.0	10.1	5.0		12.15	12.15		0.75		0.08	0.1	1.57	1.57	7°
nom		0.100	1.00	0.25	0.30	0.15	10.0	4.5	10.0	4.5	0.65	12.00	12.00	1	0.60	0.2	0.08	0.1	1.43	1.43	
min		0.050	0.95		0.25	0.12	9.9	4.0	9.9	4.0		11.85	11.85		0.45				1.28	1.28	0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

sot1181-2_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1181-2	---	MS-026	---		-12-09-14- 12-10-16

Fig. 1. Package outline HTQFP48 (SOT1181-2)

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3. Soldering

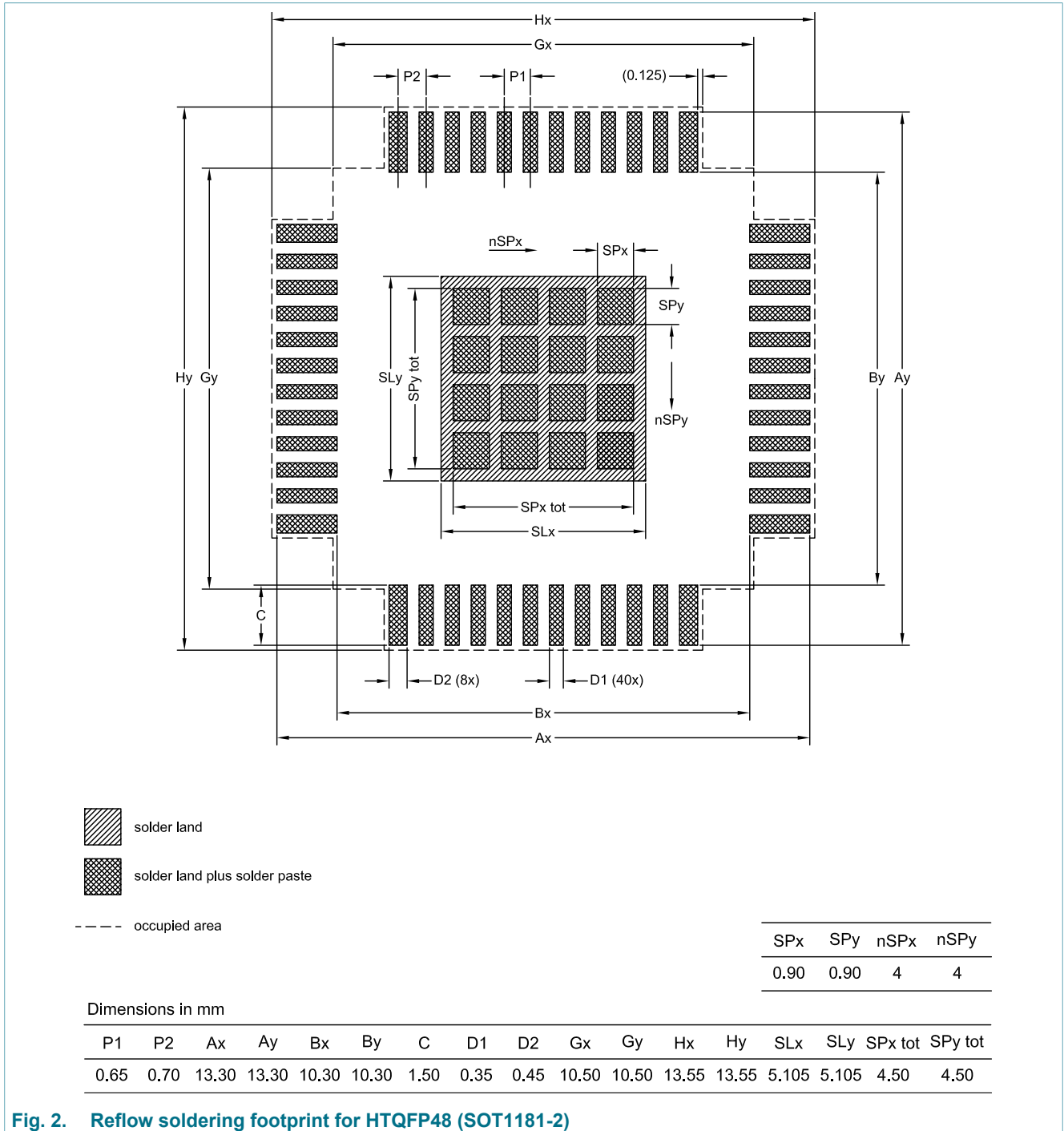


Fig. 2. Reflow soldering footprint for HTQFP48 (SOT1181-2)

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4. Legal information

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